

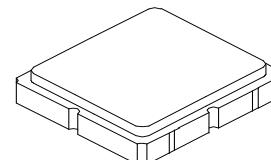
- Low-loss 1950 MHz SAW Filter
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+13	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +105	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

SF2224E

**1950 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			1950		MHz
Insertion Loss, 1920 to 1980 MHz	IL			2.3	4.0	dB
Amplitude Ripple, 1920 to 1980 MHz				1.4	2.4	dB _{P-P}
Input/Output VSWR, 1920 to 1980 MHz				1.7	2.4	
Attenuation, Referenced to 0 dB:						dB
DC to 1840 MHz			20.0	32.0		
1840 to 1900 MHz			10.0	21.0		
2000 to 2030 MHz			4.5	10.0		
2030 to 2060 MHz			20.0	47.0		
2060 to 5000 MHz			22.0	29.0		
Source Impedance	Z_s			50		Ω
Load Impedance	Z_L			50		Ω
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	960, YWWS					
Standard Reel Quantity	Reel Size 7 inch	500 Pieces/Reel				
	Reel Size 13 inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

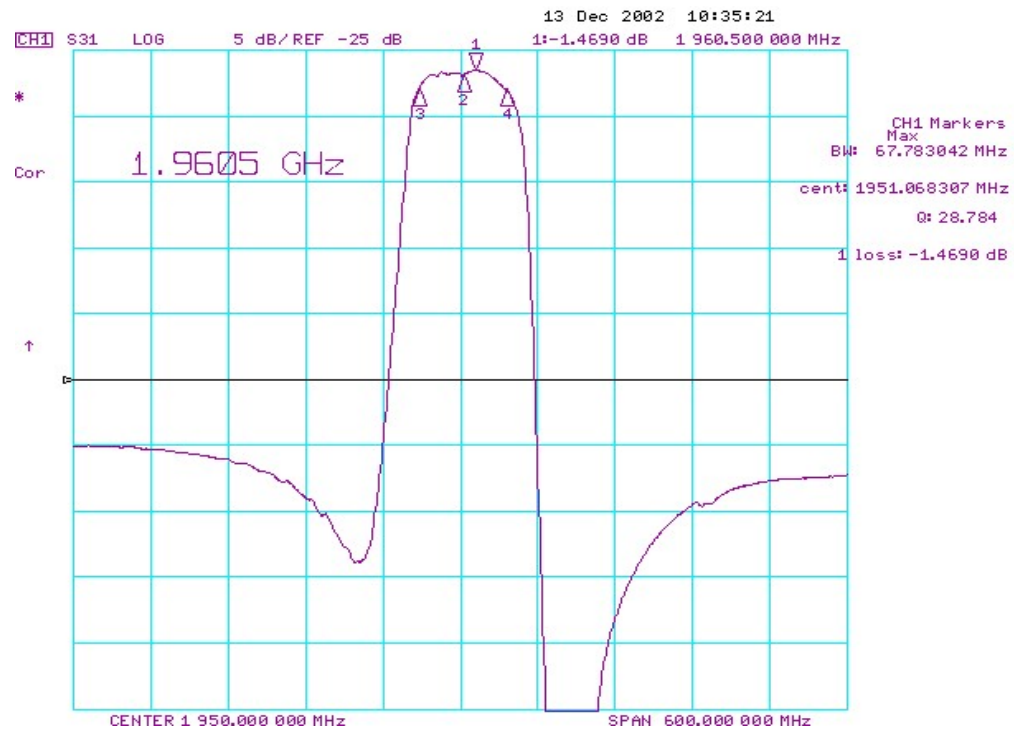


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

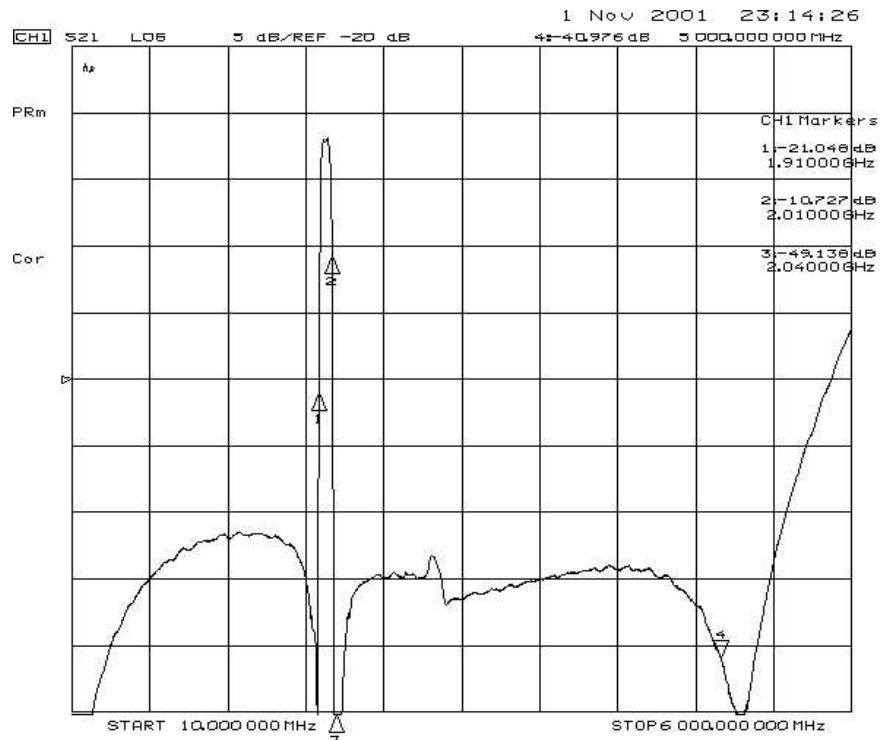
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

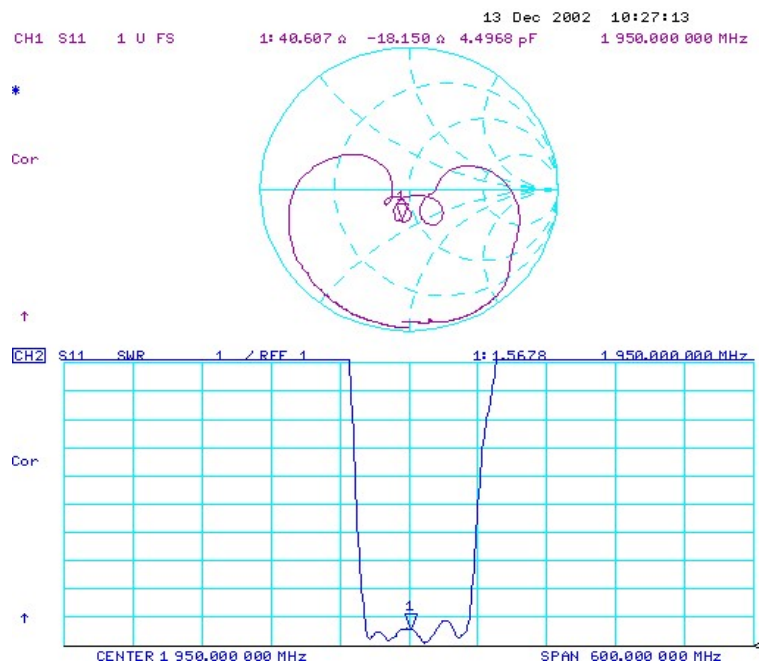
Filter Passband Response, 1650 to 2250 MHz



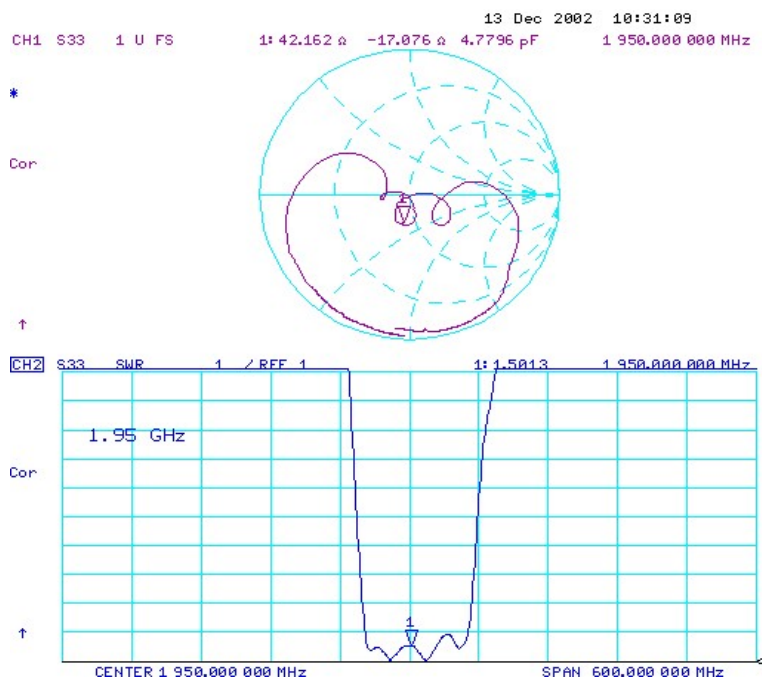
Filter Response, 10 to 6000 MHz



Filter Input Impedance

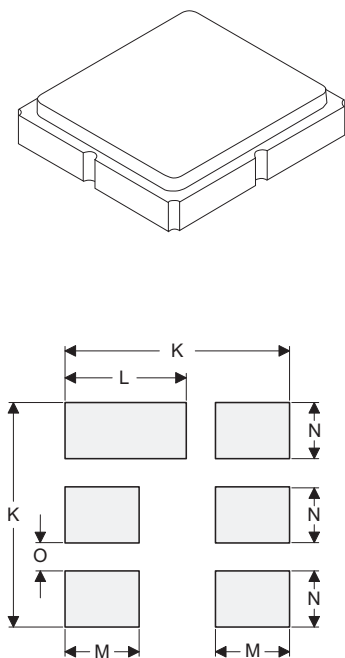


Filter Output Impedance



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

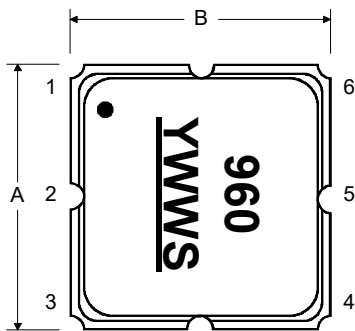
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

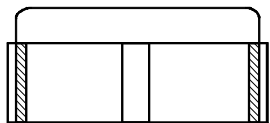
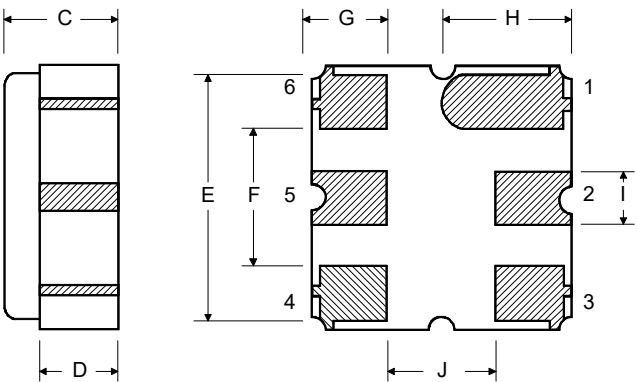
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

TOP VIEW



BOTTOM VIEW



See Detail "A"

100 REF.

"B" REF.

12.0

13.0

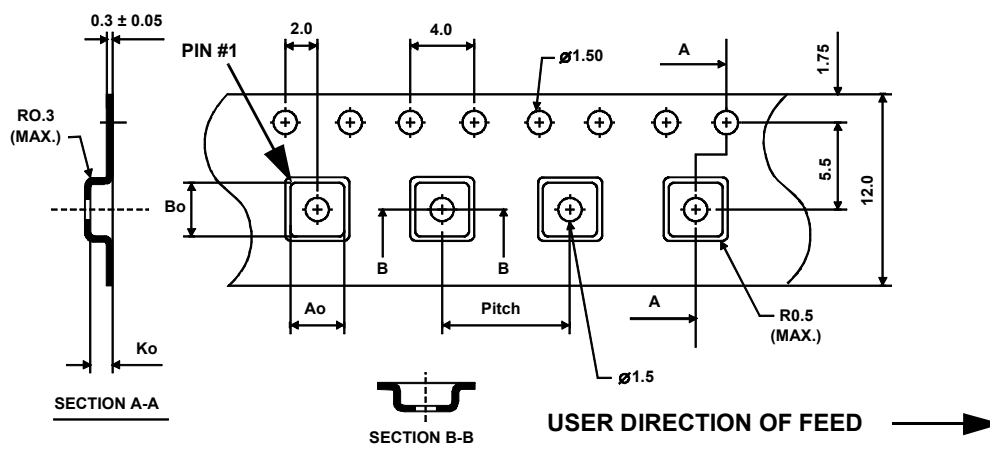
20.2

2.0

“B”		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

